

CURRENT DATE: 20-FEBRUARY-2014

TE CONNECTIVITY**PRODUCT CHANGE
NOTIFICATION**

PRODUCT CHANGE NOTIFICATION NO: E-14-002111

PCN DATE: 18-FEB-14

AGREEMENT NO:

TE CONNECTIVITY ENTITY: RMP (1082) - U.S. Operations on SAP

We would like to inform you about the following change(s) to the listed TE Connectivity Product. In case of any further questions about this change(s), please contact your TE Connectivity Sales Engineer. Affected part, drawing and/or specification numbers are listed on the attached sheet(s).

GENERAL PRODUCT DESCRIPTION:

CXP EMI Dust Cover

DESCRIPTION OF CHANGE:

Minor revision to correct finish description on drawing.

REASON FOR CHANGE:

New Product. Copper underplate on part was not specified on drawing.

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The documents listed below are being modified. Related parts that are not explicitly listed on this PCN are not being modified or discontinued per the PCN. The Last Order Date, Last Ship Date, First Date to Ship Changed Parts, and Last Date for Mixed Shipments apply only to parts explicitly on this PCN under 'PARTS BEING MODIFIED' or 'Parts being Discontinued or available with Alternates heading' (if any).

DOCUMENTATION BEING MODIFIED**CUSTOMER SPECIFIC PARTS
WITHIN THE DOCUMENT****DOCUMENTATION REVISIONS**Customer Drawing
2149126

2149126-3

Old Revision: 5